

POA FOR: LFBGA 10x10x1.4 144 F12x12 p0.8 b0.46

-4/Work Instructions and Technical/Product Specifications
Drawing/ Package Outline Assembly (POA)

Document Properties

Status	IN APPROVAL
Status Date	12-Mar-2015
Alternate Name	
Classification	ST Restricted (ALL)
Hierarchy Level & Family	-4/ Work Instructions and Technical/Product Specifications
Hierarchy Sub-level & Type/Category	Drawing/ Package Outline Assembly (POA)
Applicability	
Original ID	
Original Repository	
Business Domain	Product Development Manufacturing
Business Sub-Domain	BE Manufacturing
Plant	999F AMKOR ATC1
Production Area	Z9FA SC AMKOR - CHINA ATC1
Package Family	23 BGA <= 23 x 23
Macro Package	9Z BGA 10x10
Package	A05N LFBGA10X10X1.4 144 12SQ P.8 B.46

Document Actors

Name/Function	Role	Date
Ghidoni Marco Omar Package Development	Editor	N/A
Ghidoni Marco Omar Package Development	Responsible	N/A
Tumiati Lorenzo Documentation	Document Controller	12-Mar-2015

Referenced Document

Document ID	Document Relation	Document Title
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Revision History

Initial Release

AMS - MEMS Technology & Package Development

PACKAGE OUTLINE ASSEMBLY

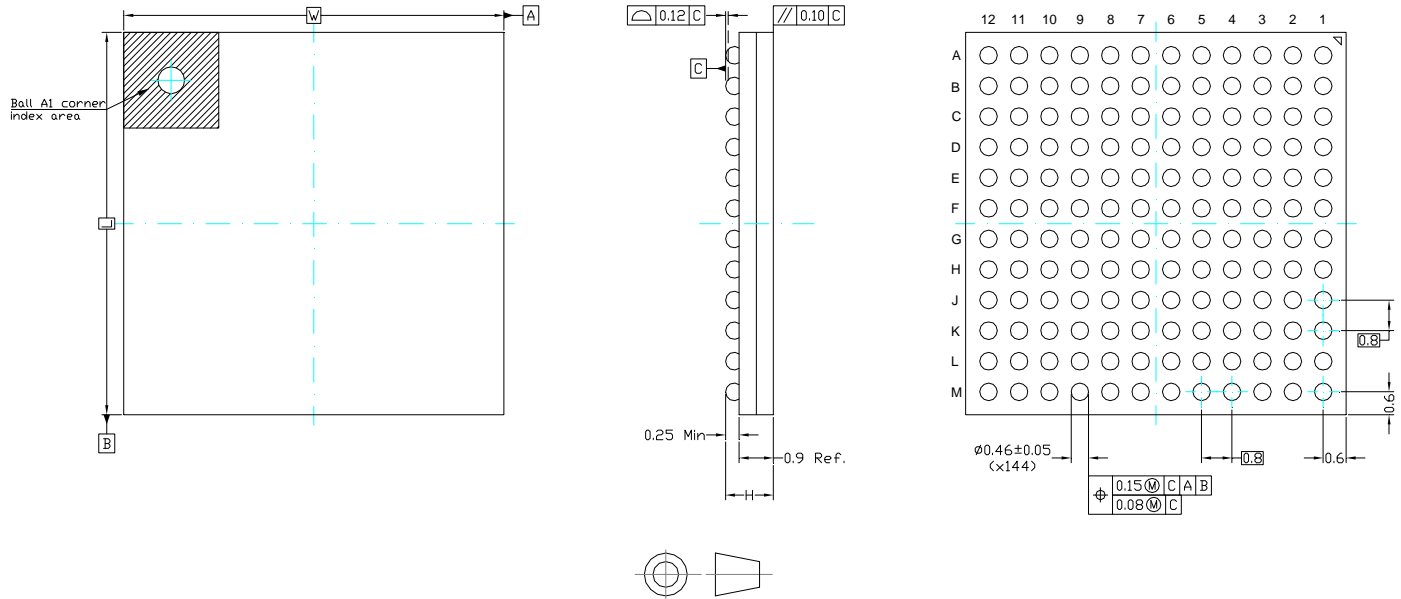
DATABOOK

TITLE: LFBGA 10mm x 10mm x 1.4MAX mm 144 F12x12 Pitch 0.8 Ball 0.46

PACKAGE TYPE: LFBGA

PACKAGE CODE: A05N

JEDEC reference: PUBLICATION 95 (JEP95) DESIGN REGISTRATION 4.5



Dimensions are in millimeter unless otherwise specified
General Tolerance is ± 0.15 mm unless otherwise specified

OUTER DIMENSIONS

ITEM	DIMENSION [mm]	TOLERANCE [mm]
Length [L]	10	± 0.1
Width [W]	10	± 0.1
Height [H]	1.4 MAX	/



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